

In re: Appln No. 09/716,146  
Attorney Docket: 6006-018  
Customer No. 29,335

### **Amendments to the Specification**

Please amend the specification, by replacing the paragraph on page 10, as follows:

Each of the above-described preferred embodiments of the present invention may be fabricated by a number of methods. In accordance with present invention, it is contemplated that ~~either forming wrought metals into the implantable device or forming the implantable devices by~~ vacuum deposition techniques are the preferred method of making the implantable structural elements of the present invention. Where an implantable device is to be fabricated of a plurality of individual tubular wire elements, such as depicted in Figures 5-7, pre-existing microtubular wire members having an outer diameter, for example, between 60 and 400 $\mu$ m and a wall thickness of between 10 and 350 $\mu$ m, may be employed to fabricate extremely small dimensioned devices suitable for intracranial or coronary artery applications. The plurality of openings passing through the wall of each of the individual tubular wire elements may be formed by microdrilling the openings through the wall and into the internal cavity or lumen of the individual tubular wire members. The plurality of openings may be laser cut, etched or formed by EDM methods, and may be formed either pre- or post- formation of the wire members into the three-dimensional conformation of the implantable device. Where an implantable device is to be formed from non-preexisting structural elements, vacuum deposition techniques may be employed to form the implantable structural body, such as sputtering, reactive ion etching, chemical vapor deposition, plasma vapor deposition, or the like, as are known in the microelectronics fabrication arts and are more fully described in co-pending, commonly assigned U.S. Patent Application Serial No. 09/443,929, filed November 19, 1999, which is hereby incorporated by reference. Because, the internal cavities and openings must be formed during deposition, the vacuum deposition techniques must be modified to deposit requisite patterns of sacrificial material to form the regions of the internal cavities and openings, over a base layer of structural material, then depositing a second layer of structural material over the sacrificial material and the base layer. The sacrificial material may then be removed, such as by etching, to leave the internal cavities and plurality of openings formed within the deposited bulk material.